

Case Study



Amkor Technology

Since its foundation in 1968, Amkor Technology has grown into one of the world's largest semiconductor manufacturers serving many of the world's leading semiconductor companies. The company is an industry leader in application-specific semiconductor package design and assembly; the right packaging being critical to ensure optimal system performance as integrated circuits continue to increase in speed and complexity. Amkor offers the industry's broadest range of package formats and sizes, from "off-the-shelf" through to highly customized designs.

Employing over 20,000 people worldwide, the company has developed expertise in high-volume manufacturing techniques and has continually diversified and expanded its operations across the globe.



Dage 4000HS bond tester. Used by Amkor Technology China to perform solder ball shear, wire pull, die shear, bump pull and zone shear tests.

“ We will continue to invest in Dage bond testing equipment as we expand our operations. I cannot recommend Dage highly enough. ”

William Zhang, Quality Assurance Manager,
Amkor Technology China



Amkor in China

The company has seen significant expansion throughout Asia with the development of production centres in strategic locations. The manufacturing facility located in Shanghai, China, focuses upon the production of laminate and leadframe packages using chip scale, plastic ball grid array, stacked die, flip chip and Amkor's MicroLeadFrame[®] format. Amkor China started using Dage bond testing equipment for their quality assurance testing in 2001. They now have multiple Dage bond testers, most of which are Dage 4000 machines, providing the facility with a uniform testing platform.

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Dage in Action

Due to the broad array of products that Amkor China manufacture, the Dage 4000 bond tester is used to carry out a wide range of applications including solder ball shear, wire pull, die shear, bump pull and zone shear. The multipurpose nature of the Dage 4000 machine has proved crucial to their operation as William Zhang, Quality Assurance Manager, Amkor Technology China explains: “It just wouldn’t be practical in terms of time, space and data correlation for us to have different machines performing separate tests. We need one system that can take care of all our testing requirements which is exactly what the Dage bond tester gives us.”

Why Dage?

When Amkor China were looking to purchase new bond testing equipment in 2001, Zhang didn’t feel the need to look at any other equipment suppliers based on his previous experience of Dage. “The quality and data accuracy of the Dage bond testing equipment is unsurpassed and their after sales support is the best in the world” enthused Zhang. “That coupled with the fact that many semiconductor companies use Dage bond testers meant there was no decision to make. Dage was the natural choice. What’s more, our operators like the easy to use ergonomic design which results in increased efficiency.”

Sound Investment

Zhang has been very impressed with every aspect of Dage and would highly recommend them. “All the way through the process from the initial installation and operator training to ongoing applications support, we have found Dage to be extremely knowledgeable, professional and responsive” concluded Zhang.

“ The quality and data accuracy of the Dage bond testing equipment is unsurpassed and their after sales support is the best in the world. For me there is no other choice of bond tester. I cannot recommend Dage highly enough. ”

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